

ABSTRACT OF THE DISCLOSURE

A method of selectively adjusting surface tension of a soldermask material.

Specifically, a method of selectively adjusting the surface tension of a soldermask material to promote adhesion of a molding compound in a ball grid array package while maintaining a low surface tension on the ball attach area to prevent bridging between the solder balls.

Solder balls require a low surface tension soldermask to minimize bridging, while the molding compound requires a high surface tension to provide adequate adhesion to the surface of the soldermask. By exposing selected portions of the soldermask to an activation method, such as ultra-violet radiation, the surface tension of the soldermask can be varied such that different areas of the package exhibit different surface tensions.